

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------------------|---------|------------------|
| L2 | 546 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/07 00:38 |
| L3 | 547 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/07 00:38 |
| L4 | 3508 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/07 00:38 |

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| L5 | 422 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate with pads and (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/07 00:39 |
| L6 | 1 | "20070190290" | US-PGPUB; USPAT | OR | ON | 2009/12/07 01:29 |
| L7 | 2 | 257/E | US-PGPUB; USPAT | OR | ON | 2009/12/07 01:30 |
| L8 | 101 | 257/E31.117 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 01:30 |
| L9 | 228 | 257/E33.068 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 01:31 |
| L10 | 1656 | 257/680 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 01:33 |
| L11 | 5017 | 257/98 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 01:35 |
| L12 | 4049 | 257/99 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 01:43 |

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|-----|------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------|----|----|---------------------|
| L13 | 2106 | 257/100 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 02:02 |
| L14 | 1951 | 257/431 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 02:20 |
| L15 | 2761 | 257/432 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 02:32 |
| L16 | 2086 | 257/433 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 02:51 |
| L17 | 836 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments or particles or powder) with (color\$3 or absorb\$3) | USPAT | OR | ON | 2009/12/07 02:53 |
| L18 | 335 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color \$3 or absorb\$3) | USPAT | OR | ON | 2009/12/07 02:53 |
| L19 | 59 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.4" near ("mm") | USPAT | OR | ON | 2009/12/07 02:59 |
| L20 | 114 | (optoelectronic or light or optical or LED or sensor or emitt\$3 or diode) with height with "0.1" near ("mm") | USPAT | OR | ON | 2009/12/07 03:02 |

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| L21 | 1221 | 257/434 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 03:11 |
| L22 | 51 | (optoelectronic or LED or sensor or emitt\$3 or diode) same (insulat\$ or dielectric) with (pigments) with (color\$3 or absorb \$3) | USPAT | OR | ON | 2009/12/07 03:13 |
| L23 | 3263 | 428/138 | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2009/12/07 03:16 |
| S1 | 15 | "4,936,808".pn. or "6,412,971".pn. or "6,373,188".pn. or "6,184,544".pn. or "6,335,545".pn. or "20040005728" or "20030160258" or "4,005,457".pn. or "20040041159" or "20020137245" or "6,291,841".pn. or "5,307,360".pn. or "20020096254" | US-PGPUB; USPAT | OR | OFF | 2009/12/05 21:31 |
| S2 | 7098 | (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (insulat\$3 or dielectric) and substrate | USPAT | OR | ON | 2009/12/05 22:08 |
| S3 | 1157 | (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate | USPAT | OR | ON | 2009/12/05 22:09 |

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| S4 | 14 | (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) near (layer or film) | USPAT | OR | ON | 2009/12/05 22:25 |
| S5 | 42 | (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) | USPAT | OR | ON | 2009/12/05 22:30 |
| S6 | 28 | S5 not S4 | USPAT | OR | ON | 2009/12/05 22:30 |
| S7 | 43 | (optoelectronic or light or optical or LED or sensor) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) | USPAT | OR | ON | 2009/12/05 22:37 |
| S8 | 1 | S7 not S5 | USPAT | OR | ON | 2009/12/05 22:37 |

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| S9 | 43 | (optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) | USPAT | OR | ON | 2009/12/05 22:38 |
| S10 | 51 | (optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (wire or conductive or metal\$2) | USPAT | OR | ON | 2009/12/05 22:38 |
| S11 | 9 | S10 not S5 | USPAT | OR | ON | 2009/12/05 22:38 |
| S12 | 19 | (optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (edge or perimeter or boundary) with (pad) | USPAT | OR | ON | 2009/12/05 22:41 |

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| S13 | 405 | (optoelectronic or light or optical or LED or sensor or emitt\$3) with (semiconductor or die or dice or chip or IC) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/05 22:49 |
| S14 | 1 | ("2004/0041159").URPN. | USPAT | OR | OFF | 2009/12/05 23:14 |
| S15 | 9 | ("5261013" "5323084" "5656847" "6153448" "6482664" "6504180" "6570180" "6593598" "6744194").PN. OR ("7078737").URPN. | US-PGPUB; USPAT; USOCR | OR | OFF | 2009/12/05 23:16 |
| S16 | 543 | (optoelectronic or light or optical or LED or sensor or emitt\$3) with (within or cover\$3 or surround\$3 or embedded) with (insulat\$3 or dielectric or resin) and substrate and (soptoelectronic or light or optical) with (semiconductor or die or dice or chip or IC) with (conduct\$3 or metal\$3 or wire) with (surround\$3 or side) | USPAT | OR | ON | 2009/12/05 23:17 |
| S17 | 138 | S16 not S13 | USPAT | OR | ON | 2009/12/05 23:17 |

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